	Туре	Hits	Search Text
1	BRS	444	(semiconductor nearl (device package)) and ((tape near carrier) with (opening hole))
2	BRS	186	((semiconductor nearl (device package)) and ((tape near carrier) with (opening hole))) and (bump ball)
3	BRS	122	(semiconductor nearl (device package)) and ((tape near carrier) with opening)
4	BRS	59	((semiconductor nearl (device package)) and ((tape near carrier) with opening)) not (((semiconductor nearl (device package)) and ((tape near carrier) with (opening hole))) and (bump ball))
5	BRS	480	(semiconductor nearl (device package)) and (((tape film) nearl (carrier substrate)) with opening)
6	BRS	691	(semiconductor nearl (device package)) and (tape nearl carrier) and (bump ball)
7	BRS	712	(semiconductor nearl (device package)) and ((tape nearl carrier) (film nearl substrate)) and (bump ball)
8	BRS	67	((semiconductor nearl (device package)) and (tape nearl carrier) and (bump ball)) and (sealing near resin)
9	BRS	89	((semiconductor nearl (device package)) and ((tape nearl carrier) (film nearl substrate)) and (bump ball)) and (sealing near resin)
10	BRS	824	<pre>(semiconductor near1 (device package)) and ((tape near1 carrier) (film near1 substrate) (film near carrier)) and (bump ball)</pre>
11	BRS	103	((semiconductor near1 (device package)) and ((tape near1 carrier) (film near1 substrate) (film near carrier)) and (bump ball)) and (sealing near resin)

	DBs	Time Stamp	Comments	Error Definition
	USPAT; EPO; JPO; Derwent	2001/03/02 09:04		
, ,	USPAT; EPO; JPO; Derwent	2001/02/28 14:19		
	USPAT; EPO; JPO; Derwent	2001/02/28 14:32		
171	USPAT; EPO; JPO; Derwent	2001/02/28 14:48		
5	USPAT; EPO; JPO; Derwent	2001/03/03 09:33		
6	USPAT; EPO; JPO; Derwent	2001/03/01 08:01		
7	USPAT	2001/03/01 08:08		
8	USPAT	2001/03/01 08:07		
9	USPAT	2001/03/01 08:34		
10	USPAT	2001/03/01 08:17		
11	USPAT	2001/03/01 08:35		

	Туре	Hits	Search Text
12	BRS	14	<pre>(((semiconductor nearl (device package)) and ((tape nearl carrier) (film nearl substrate) (film near carrier)) and (bump ball)) and (sealing near resin)) not (((semiconductor nearl (device package)) and ((tape nearl carrier) (film nearl substrate)) and (bump ball)) and (sealing near resin))</pre>
13	BRS	111	(semiconductor nearl (device package)) and tab and (thin near package)
14	BRS	8	kitahiro adj isamu.in.
15	BRS	280	(takahashi adj hiroshi.in.) (kitahiro adj isamu.in.)
16	BRS	169	(semiconductor near chip) and (((tape film) nearl (carrier substrate)) with opening)
17	BRS	0	((semiconductor near chip) and (((tape film) nearl (carrier substrate)) with opening)) and (stress near neutral near plane)
18	BRS	23	stress near neutral near plane
19	BRS	71	"4460825" "4829666" "4746392"
20	BRS	111	hoppe adj joachim.in.
21	BRS	106	(hoppe adj joachim.in.) not (("4460825" "4829666" "4746392") and "4746392" and "4460825")
22	BRS	95	(hoppe adj joachim.in.) not (("4460825" "4829666" "4746392") "4746392" "4460825")
23	BRS	0	5196917.pn. and vent
24	BRS	3	5196917.pn.
25	BRS	3	5196917.pn. and (air vent hole)
26	BRS	12	<pre>(((tape adj carrier) (film near carrier) (film near substrate)) with (lead (metal near layer) (conductive near layer)) with (electroplated electroplating))</pre>
27	BRS	2057	((tape adj carrier) (film near carrier) (film near substrate)) and mold

	DBs	Time Stamp	Comments	Error Definition	
12	USPAT	2001/03/01 08:35			
13	USPAT; EPO; JPO; Derwent	2001/03/02 08:32			
14	USPAT	2001/03/02 08:53			
15	USPAT	2001/03/02 08:53			
16	USPAT; EPO; JPO; Derwent	2001/03/02 09:51			
17	USPAT; EPO; JPO; Derwent	2001/03/02 09:52			
18	USPAT; EPO; JPO; Derwent	2001/03/02 09:53			
19	USPAT; EPO; JPO	2001/03/02 10:38			
20	USPAT; EPO; JPO	2001/03/02 10:39			
21	USPAT; EPO; JPO	2001/03/02 10:40			
22	USPAT; EPO; JPO	2001/03/02 10:40			
23	USPAT; EPO; JPO; Derwent	2001/03/02 14:10			
24	USPAT; EPO; JPO; Derwent	2001/03/02 14:10			
25	USPAT; EPO; JPO; Derwent	2001/03/02 14:11			
26	USPAT	2001/03/03 10:03			
27	USPAT	2001/03/03 10:18			

	Туре	_ Hits	Search Text
28	BRS	39	(((tape adj carrier) (film near carrier) (film near substrate)) and mold) and ((air adj vent) (vent adj hole))

	ŧ	DBs	Time Stamp	Comments	Error Definition
28	USPAT		2001/03/03 10:18		